TOSHIBA Field Effect Transistor Silicon N Channel MOS Type ( $L^2$ - $\pi$ -MOSV)

# 2SK2232

# Chopper Regulator, DC-DC Converter and Motor Drive Applications

• 4 V gate drive

• Low drain-source ON resistance :  $RDS(ON) = 36 \text{ m}\Omega \text{ (typ.)}$ 

• High forward transfer admittance  $|Y_{fs}| = 16 \text{ S (typ.)}$ 

• Low leakage current :  $IDSS = 100 \mu A (max) (VDS = 60 V)$ 

• Enhancement-mode :  $V_{th} = 0.8 \sim 2.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$ 

#### **Maximum Ratings (Ta = 25°C)**

Characteri	stics	Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	60	V	
Drain-gate voltage (R	<sub>GS</sub> = 20 kΩ)	$V_{DGR}$	60	V	
Gate-source voltage		V <sub>GSS</sub>	±20	V	
Drain current	DC (Note 1)	I <sub>D</sub>	25	Α	
Diain current	Pulse (Note 1)	I <sub>DP</sub>	100	Α	
Drain power dissipatio	n (Tc = 25°C)	P <sub>D</sub>	35	W	
Single pulse avalanche energy (Note 2)		E <sub>AS</sub>	156	mJ	
Avalanche current		I <sub>AR</sub>	25	Α	
Repetitive avalanche	energy (Note 3)	E <sub>AR</sub>	3.5	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature r	ange	T <sub>stg</sub>	-55~150	°C	

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Weight: 1.9 g (typ.)

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	3.57	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	62.5	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:  $V_{DD}$  = 25 V,  $T_{ch}$  = 25°C (initial), L = 339  $\mu$ H,  $R_{G}$  = 25  $\Omega$ ,  $I_{AR}$  = 25 A

Note 3: Repetitive rating; Pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device.

Please handle with caution.

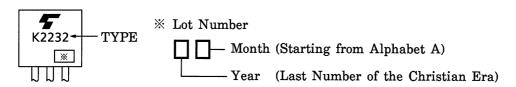
## **Electrical Characteristics (Ta = 25°C)**

Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0 V	_	_	±10	μΑ
Drain cut-off cu	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V	_	_	100	μΑ
Drain-source br voltage	eakdown	V <sub>(BR) DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	60	_	1	V
Gate threshold v	voltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	0.8	_	2.0	V
Drain course ON registers		Pro (ON)	V <sub>GS</sub> = 4 V, I <sub>D</sub> = 12 A		0.057	0.08	Ω
Drain-source ON resistance	R <sub>DS</sub> (ON)	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 12 A	_	0.036	0.046		
Forward transfe	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 12 A	10	16	_	S
Input capacitano	e	C <sub>iss</sub>		_	1000	_	
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	-	200	_	pF
Output capacitance		Coss			550	_	
Switching time	Rise time	t <sub>r</sub>	$V_{GS} = 10V \qquad I_{D} = 12A \qquad \text{OVOUT}$ $R_{L} = 2.5\Omega$ $V_{DD} = 30V$	_	20	_	
	Turn-on time	t <sub>on</sub>		_	30	_	no
	Fall time	t <sub>f</sub>		_	55	_	- ns -
	Turn-off time	t <sub>off</sub>	Duty $\leq 1\%$ , $t_{\rm W} = 10 \mu \rm s$	_	130	_	
Total gate charge (Gate-source plus gate-drain)		Qg			38		
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \approx 48 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 25 \text{ A}$		25	_	nC
Gate-drain ("miller") charge		Q <sub>gd</sub>			13	_	

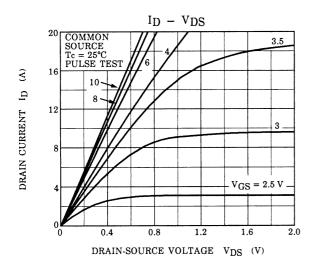
## **Source-Drain Ratings and Characteristics (Ta = 25°C)**

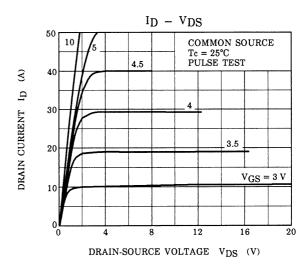
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	_	25	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_	_	100	Α
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 25 A, V <sub>GS</sub> = 0 V	_	_	-1.8	V
Reverse recovery time	t <sub>rr</sub>	$I_{DR}$ = 25 A, $V_{GS}$ = 0 V, $dI_{DR}$ / $dt$ = 50 A / $\mu$ s	1	50	_	ns
Reverse recovered charge	Q <sub>rr</sub>			35	_	μC

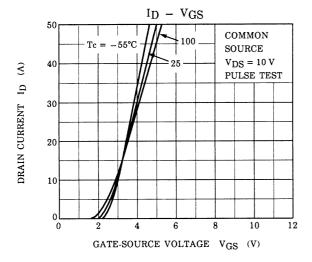
### Marking

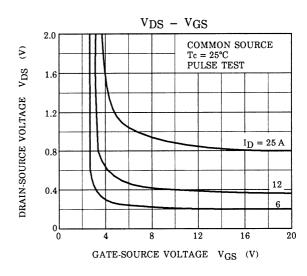


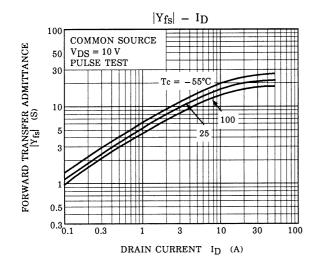
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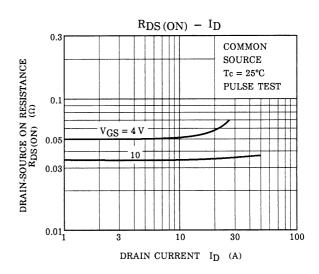




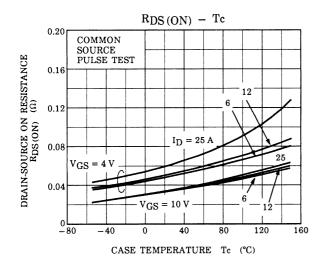


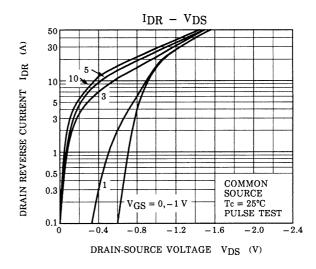


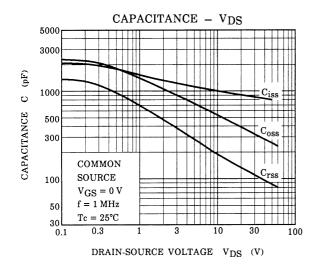


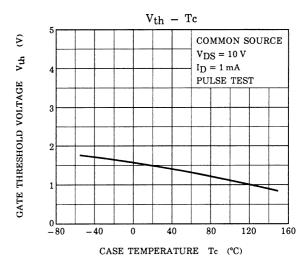


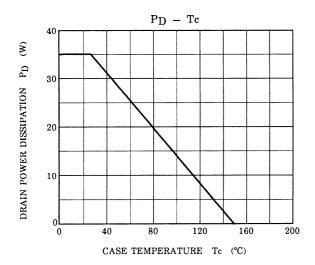
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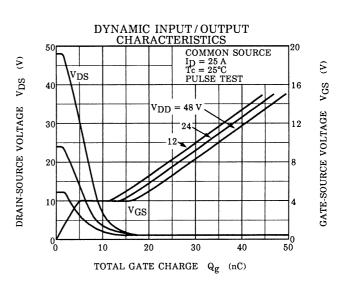




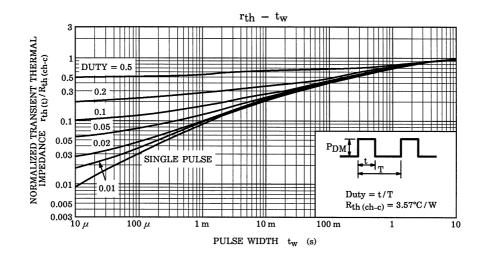


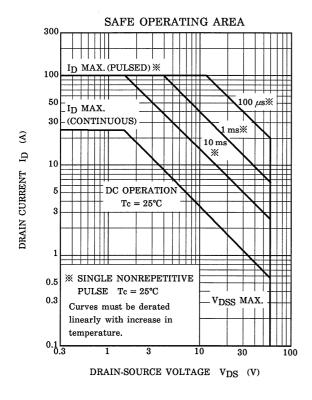


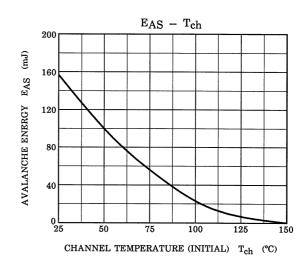


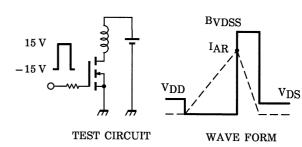


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$$R_G = 25 \Omega$$
  
 $V_{DD} = 25 V$ ,  $L = 339 \mu H$ 

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^{2} \cdot \left( \frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right)$$

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